ASSOCIATION ELECTRONICS	CONNECTING CONNECTING NDUSTRIES® international and Par	PC, Bannockb	ourn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat he declaration e	ion of th encompa	ne substances asses all low	within the er level mate	manufactur erials for wh	er listed it hich the m	em. Note: if anufacturer	f the item is an as has engineering	sembly with low responsibility.
752-21.1	1.1 IPC Web Site for Information on IPC-1752 Standard Form Type Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier	Information														
Company name* Company unique ID					1	Unique ID Authority					Response Date*				
nsemi											2023-06-08				
Contact Na	ame		Title - Contact			]	Phone - Contact*					Email - Contact*			
Product-E	nv-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorized	l Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*					
roduct-E	nv-Stewards	Product Envi	Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number	Number Mfr Item Name			Effective Date	Vers	ion	Manufacturing Site		V	Veight*	UOM	Unit Type
		STK541UC62K-E 3phase inverter HI		IC		2023-06-08 VN2			1	4300.0	mg	Each			
Ianufac	cturing Proccess Informa	tion													
-	Terminal Plating / Grid Array Material		Cerminal Base	Alloy J	J-STD-020 MSL Rat		Peak Process Body Temperatu		ire Max Ti	me at Peak	Temperate	are Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alle		CU Alloy	1	NA		0		С	30		second	is 3			
omments															
or more in	nformation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (		dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-ethers)						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company	ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the	henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r	stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co	ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of					
<b>RoHS Declaration *</b> 4 - Item(s	) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7c-I Electrical and electronic c	omponents containing lead in a glass o	r ceramic other than dielectric ceramic	in capacitors,	e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	4682.79	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		58.5349	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		230.8615	mg
			В	Nickel (Ni)	7440-02-0		7.9607	mg
			Supplier	Acrylic resins	Proprietary Data		3.278	mg
			Supplier	Copper (Cu)	7440-50-8		314.6835	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.3414	mg
			Supplier	Aluminum (Al)	7429-90-5		4065.1299	mg
Thip Parts	42.22	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.2539	mg
			Supplier	Silver (Ag)	7440-22-4		1.0808	mg
			Supplier	Epoxy resins	129915-35-1		0.3462	mg
			Supplier	Tin (Sn)	7440-31-5		1.1315	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0633	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.7642	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		6.1726	mg
			Supplier	Phenolic resins	Proprietary Data		0.0549	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0169	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		25.5515	mg
			В	Nickel (Ni)	7440-02-0		3.1201	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.0507	mg
			Supplier	Copper (Cu)	7440-50-8		2.3179	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2955	mg
Die	30.01	mg	Supplier	Silicon (Si)	7440-21-3		30.01	mg
Die Attach	1.57	mg	Supplier	Silver (Ag)	7440-22-4		1.2089	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.2669	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0675	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0267	mg
ead Frame	785.4	mg	Supplier	Iron (Fe)	7439-89-6		0.7854	mg
			Supplier	Copper (Cu)	7440-50-8		784.379	mg
			Supplier	Phosphorus (P)	7723-14-0		0.2356	mg
Iold Compound-Black	8646.76	mg		Brominated epoxy resin	proprietary data		172.9352	mg
			Supplier	Phenolic Resin	Proprietary Data		518.8056	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	Epoxy Phenol Resin	Proprietary Data	172.9352	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4	259.4028	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	864.676	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	605.2732	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	6052.7319	mg
Plating	21.09	mg	Supplier	Tin (Sn)	7440-31-5	11.1904	mg
			В	Nickel (Ni)	7440-02-0	9.8996	mg
Solder Ball	45.67	mg	Supplier	Silver (Ag)	7440-22-4	1.4021	mg
			Supplier	Tin (Sn)	7440-31-5	43.9345	mg
			В	Antimony (Sb)	7440-36-0	0.0091	mg
			Supplier	Copper (Cu)	7440-50-8	0.3243	mg
Wire Bond	44.49	mg	Supplier	Silicon (Si)	7440-21-3	0.0044	mg
			Supplier	Aluminum (Al)	7429-90-5	44.4856	mg